

Gap Pad

Product Name	Description	Key Attributes	Thermal Conductivity (W/m • K)	Modulus at 25°C (kPa)	Dielectric Breakdown Voltage	Thickness (mm)	Flammability Rating
BERGQUIST GAP PAD 1000SF	Silicone-free, thermally conductive gap filling material	- No silicone outgassing - No silicone extraction - Reduced tack on one side to aid in application assembly - Electrically isolating	0.9	234	6,000 V at 250 µm	• 0.254 – 3.175	UL 94 V-1
BERGQUIST GAP PAD 2200SF	Silicone-free, thermally conductive gap filling material	- Medium compliance with easy handling - Electrically isolating	2	228	5,000 V at 250 µm	• 0.254 – 3.175	UL 94 V-0
BERGQUIST GAP PAD 2202SF	Silicone-free, high performance, thermally conductive gap filling material	- Minimal compression set 12.7 µm film provides tack-free surface - Tacky side allows for ease of handling and placement	2	1,500	5,000 V at 250 µm	• 0.254 – 3.175	UL 94 V-0
BERGQUIST GAP PAD 3004SF	Silicone-free, high performance, thermally conductive gap filling material	- Excellent thermal performance 6.4 µm polyethylene terephthalate (PET) provides easy disassembly, leaving no residue - Tacky side allows for ease of handling and placement	3	2,450	6,000 V at 250 µm	• 0.254 – 3.175	UL 94 V-0
BERGQUIST GAP PAD HC3.0	Thermally conductive gap filling material	- High-compliance, low compression stress - Fiberglass reinforced for shear and tear resistance - Low modulus	3	110	5,000 V at 500 µm	• 0.508 – 3.175	UL 94 V-0
BERGQUIST GAP PAD HC5.0	Thermally conductive gap filling material	- Highly conformable - Exceptional thermal performance - High-compliance, low compression stress - Fiberglass reinforced for shear and tear resistance - Low modulus	5	121	5,000 V at 500 µm	• 0.508 • 1.016 • 1.524 • 2.032 • 2.540 • 3.175	UL 94 V-0
BERGQUIST GAP PAD VO ULTRA SOFT	Thermally conductive gap filling material	- Highly conformable, low hardness “Gel-like” modulus - Decreased strain - Puncture, shear and tear resistant - Electrically isolating	1	55	6,000 V at 500 µm	• 0.508 – 6.350	UL 94 V-0